

BAV70TT1

Preferred Device

Dual Switching Diode

Features

- Pb-Free Package May be Available.* The G-Suffix Denotes a Pb-Free Lead Finish

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Rating	Symbol	Max	Unit
Reverse Voltage	V_R	70	Vdc
Forward Current	I_F	200	mAdc
Peak Forward Surge Current	$I_{FM}(\text{surge})$	500	mAdc

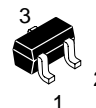
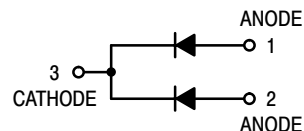
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (1) $T_A = 25^\circ\text{C}$ Derated above 25°C	P_D	225	mW
Thermal Resistance, Junction to Ambient (1)	$R_{\theta JA}$	555	$^\circ\text{C}/\text{W}$
Total Device Dissipation, FR-4 Board (2) $T_A = 25^\circ\text{C}$ Derated above 25°C	P_D	360	mW
Thermal Resistance, Junction-to-Ambient (2)	$R_{\theta JA}$	345	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

- FR-4 @ Minimum Pad
- FR-4 @ 1.0×1.0 Inch Pad

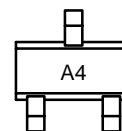


ON Semiconductor®

<http://onsemi.com>

CASE 463
SOT-416/SC-75
STYLE 3

DEVICE MARKING



ORDERING INFORMATION

Device	Package	Shipping†
BAV70TT1	SOT-416	3000 / Tape & Reel
BAV70TT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

Preferred devices are recommended choices for future use and best overall value.

BAV70TT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage ($I_{(BR)} = 100 \mu\text{Adc}$)	$V_{(BR)}$	70	–	Vdc
Reverse Voltage Leakage Current (Note 3) ($V_R = 70 \text{ Vdc}$) ($V_R = 50 \text{ Vdc}$)	I_R I_R	– –	5.0 100	μAdc nAdc
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	C_D	–	1.5	pF
Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$)	V_F	– – – –	715 855 1000 1250	mVdc
Reverse Recovery Time ($I_F = I_R = 10 \text{ mAdc}, R_L = 100 \Omega, I_{R(REC)} = 1.0 \text{ mAdc}$) (Figure 1)	t_{rr}	–	6.0	ns
Forward Recovery Voltage ($I_F = 10 \text{ mAdc}, t_r = 20 \text{ ns}$) (Figure 2)	V_{RF}	–	1.75	V

3. For each individual diode while the second diode is unbiased.

BAV70TT1

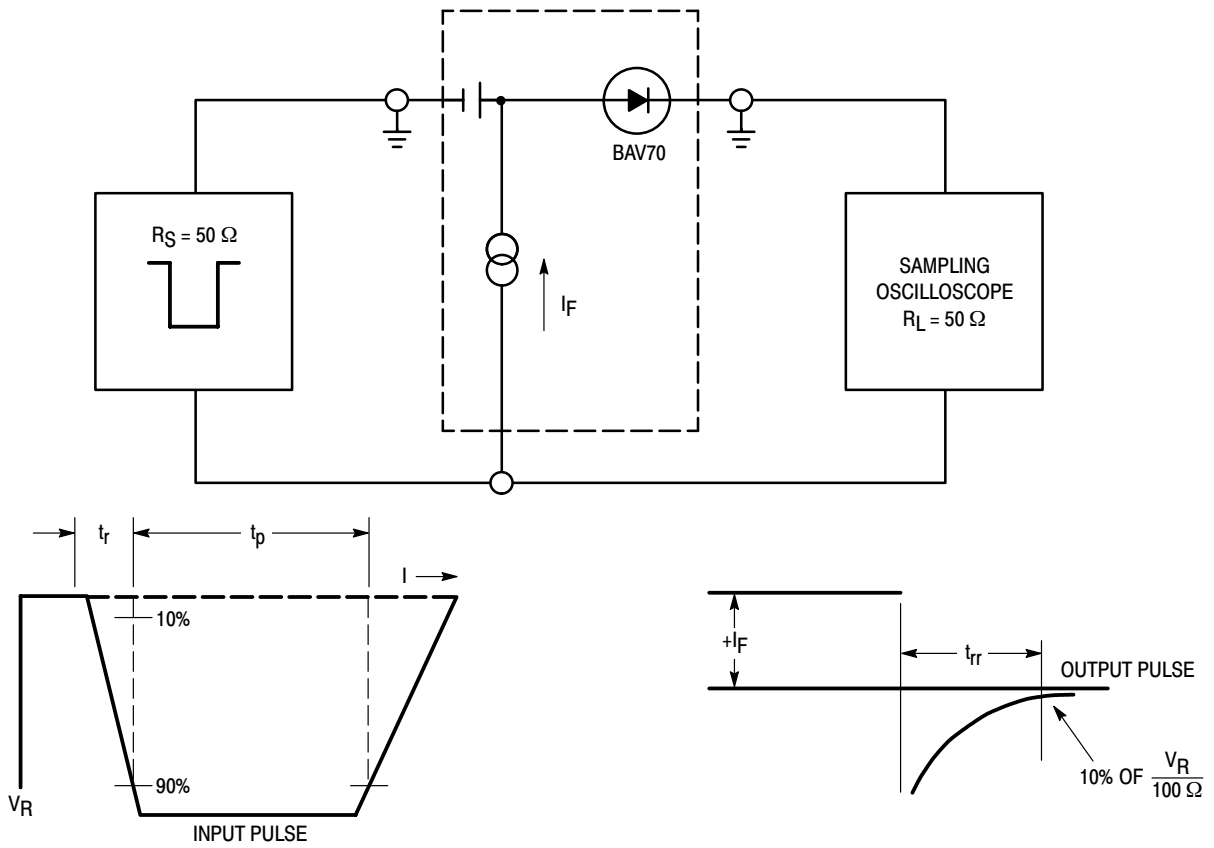


Figure 1. Recovery Time Equivalent Test Circuit

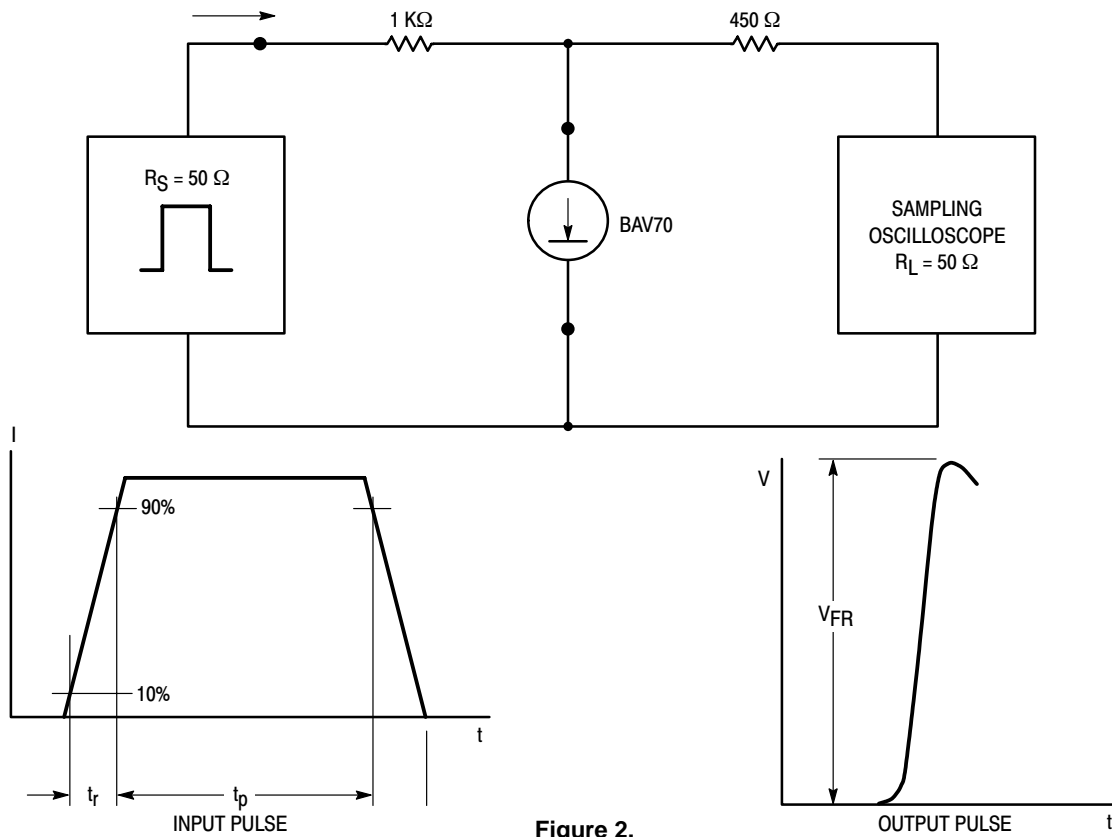


Figure 2.

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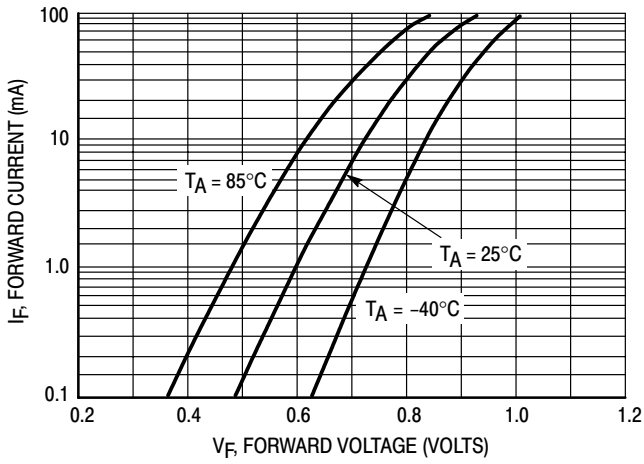


Figure 3. Forward Voltage

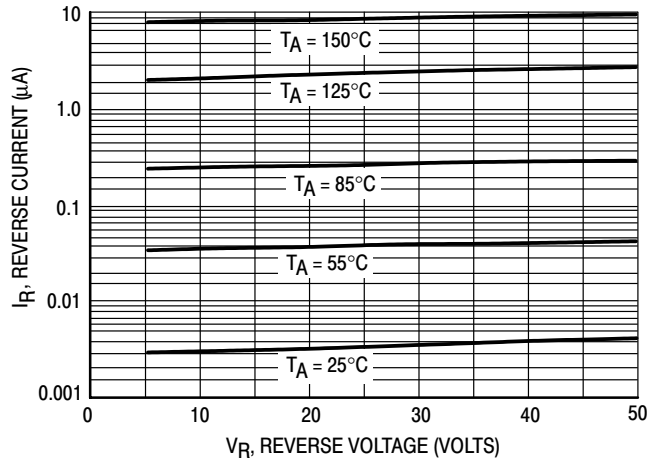


Figure 4. Leakage Current

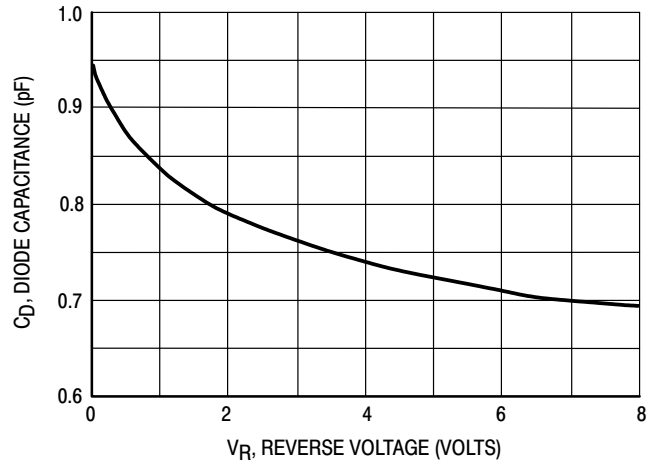


Figure 5. Capacitance

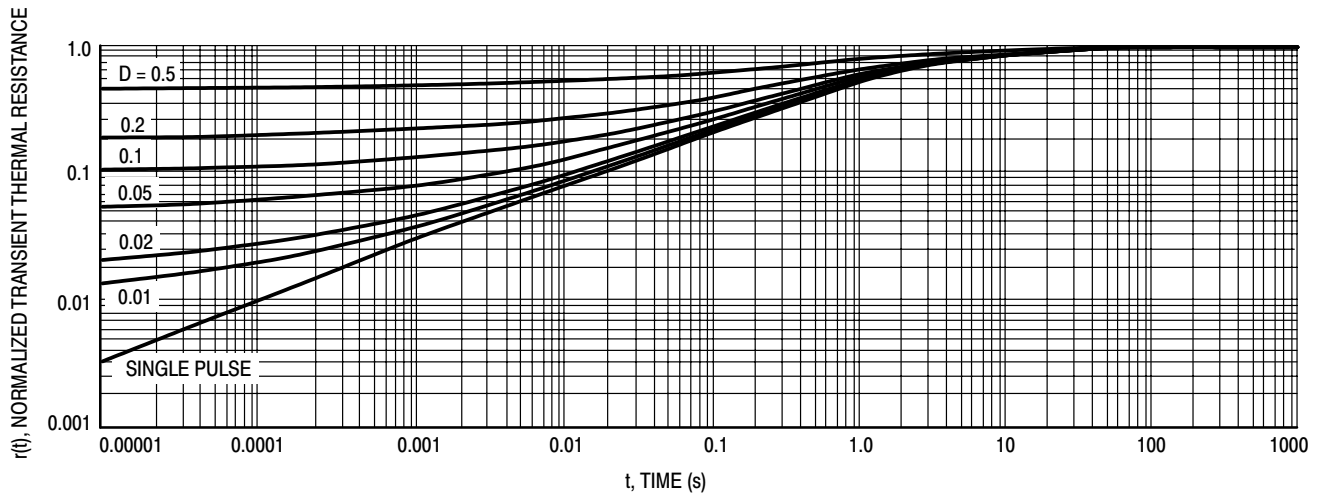
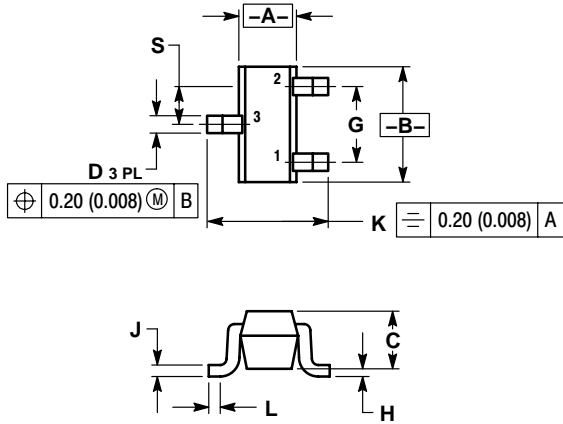


Figure 6. Normalized Thermal Response

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PACKAGE DIMENSIONS

SC-75 (SC-90, SOT-416)
CASE 463-01
ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
B	1.40	1.80	0.055	0.071
C	0.60	0.90	0.024	0.035
D	0.15	0.30	0.006	0.012
G	1.00 BSC		0.039 BSC	
H	---	0.10	---	0.004
J	0.10	0.25	0.004	0.010
K	1.45	1.75	0.057	0.069
L	0.10	0.20	0.004	0.008
S	0.50 BSC		0.020 BSC	

STYLE 3:

- PIN 1. ANODE
- ANODE
- CATHODE

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